

Electronic Patent Application Fee Transmittal

Application Number:	10666399			
Filing Date:	18-Sep-2003			
Title of Invention:	Molded chip fabrication method and apparatus			
First Named Inventor/Applicant Name:	Michael S. Leung			
Filer:	Brian J. Philpott/Joan Harriman			
Attorney Docket Number:	P0298US-7			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810